

August 2010

FGPF4536 360V, PDP IGBT

Features

- · High current capability
- Low saturation voltage: $V_{CE (sat)} = 1.59 \text{ V} @ I_{C} = 50 \text{ A}$
- · High input impedance
- Fast switching
- · RoHS compliant

Application

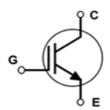
• PDP System



General Description

Using Novel Trench IGBT Technology, Fairchild's new series of trench IGBTs offer the optimum performance for PDP applications where low conduction and switching losses are essential.





Absolute Maximum Ratings

| Symbol | Description | | Ratings | Units | |
|--------------------------|---|------------------------|-------------|-------|--|
| V _{CES} | Collector to Emitter Voltage | | 360 | V | |
| V _{GES} | Gate to Emitter Voltage | | ± 30 | V | |
| I _{C pulse(1)*} | Pulsed Collector Current | $@ T_C = 25^{\circ}C$ | 220 | А | |
| P _D | Maximum Power Dissipation | $@ T_C = 25^{\circ}C$ | 28.4 | W | |
| | Maximum Power Dissipation | $@ T_C = 100^{\circ}C$ | 11.4 | W | |
| T _J | Operating Junction Temperature | | -55 to +150 | °C | |
| T _{stg} | Storage Temperature Range | | -55 to +150 | °C | |
| TL | Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds | | 300 | °C | |

Thermal Characteristics

| Symbol | Parameter | Тур. | Max. | Units | |
|-----------------------|---|------|------|-------|--|
| $R_{\theta JC}(IGBT)$ | Thermal Resistance, Junction to Case | - | 4.4 | °C/W | |
| $R_{\theta JA}$ | Thermal Resistance, Junction to Ambient | | 62.5 | °C/W | |

Notes

(1) Half Sine Wave, D < 0.01, pluse width < $5\mu sec$

^{*} lc_pluse limited by max Tj

Package Marking and Ordering Information

| Device Marking | Device | Package | Packaging Type | Qty per Tube | Max Qty per Box | |
|----------------|------------|---------|-------------------|--------------|--------------------|--|
| FGPF4536 | FGPF4536TU | TO-220F | Tube | 50ea | = | |

Electrical Characteristics of the IGBT T_C = 25°C unless otherwise noted

| Symbol | Parameter | Test Conditions | Min. | Тур. | Max. | Units |
|---|--|--|------|------|------|-------|
| Off Charac | teristics | | • | • | • | |
| BV _{CES} | Collector to Emitter Breakdown Voltage | $V_{GE} = 0V, I_{C} = 250\mu A$ | 360 | - | - | V |
| $\Delta BV_{CES} \over \Delta T_J$ | Temperature Coefficient of Breakdown Voltage | $V_{GE} = 0V, I_{C} = 250\mu A$ | - | 0.4 | - | V/°C |
| I _{CES} | Collector Cut-Off Current | $V_{CE} = V_{CES}, V_{GE} = 0V$ | - | - | 100 | μΑ |
| I _{GES} | G-E Leakage Current | $V_{GE} = V_{GES}, V_{CE} = 0V$ | - | - | ±400 | nA |
| On Charac | teristics | | | | | |
| V _{GE(th)} | G-E Threshold Voltage | $I_{C} = 250 \mu A, V_{CE} = V_{GE}$ | 2.4 | 3.3 | 4.0 | V |
| () | | I _C = 20A, V _{GE} = 15V | - | 1.19 | - | V |
| V | Collector to Emitter | I _C = 30A, V _{GE} = 15V | - | 1.33 | _ | V |
| V _{CE(sat)} Collector to Emitter Saturation Voltage | | I _C = 50A, V _{GE} = 15V, T _C = 25°C | - | 1.59 | 1.8 | V |
| | | I _C = 50A, V _{GE} = 15V, T _C = 125°C | - | 1.66 | - | V |
| Dynamic C | haracteristics | | | | | |
| C _{ies} | Input Capacitance | | - | 1295 | - | pF |
| C _{oes} | Output Capacitance | $V_{CE} = 30V_{,} V_{GE} = 0V_{,}$ f = 1MHz | - | 56 | - | pF |
| C _{res} | Reverse Transfer Capacitance | 1 - 1W112 | - | 43 | - | pF |
| Switching | Characteristics | | | | | |
| t _{d(on)} | Turn-On Delay Time | | - | 5 | - | ns |
| t _r | Rise Time | $V_{CC} = 200V, I_{C} = 20A,$ $R_{G} = 5\Omega, V_{GE} = 15V,$ | - | 20 | - | ns |
| t _{d(off)} | Turn-Off Delay Time | ResistiveLoad, T _C =25°C | - | 41 | - | ns |
| t _f | Fall Time | | - | 182 | - | ns |
| t _{d(on)} | Turn-On Delay Time | | - | 4.6 | - | ns |
| t _r | Rise Time | $V_{CC} = 200V, I_{C} = 20A,$ $R_{G} = 5\Omega, V_{GE} = 15V,$ | - | 21 | - | ns |
| t _{d(off)} | Turn-Off Delay Time | Resistive Load, $T_C = 125^{\circ}C$ | - | 43 | - | ns |
| t _f | Fall Time | | - | 249 | - | ns |
| Qg | Total Gate Charge | V _{CE} = 200V _. I _C = 20A, | - | 47 | - | nC |
| Q _{ge} | Gate to Emitter Charge | $V_{CE} = 200V_{1C} = 20A_{1}$ $V_{GE} = 15V$ | - | 5.4 | - | nC |
| Q _{gc} | Gate to Collector Charge | | - | 15 | - | nC |

Figure 1. Typical Output Characteristics

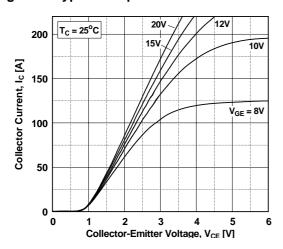


Figure 3. Typical Saturation Voltage Characteristics

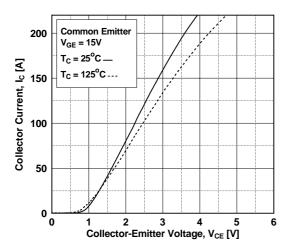


Figure 5. Saturation Voltage vs. Case
Temperature at Variant Current Level

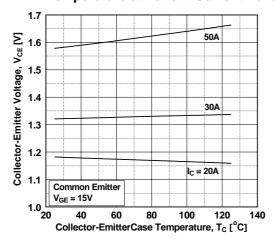


Figure 2. Typical Output Characteristics

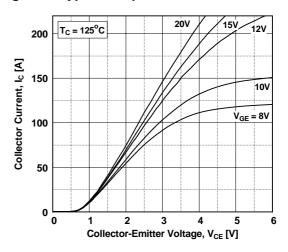


Figure 4. Transfer Characteristics

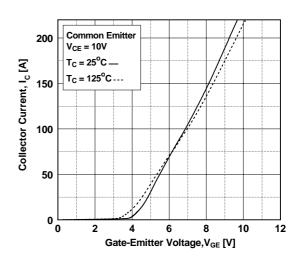


Figure 6. Saturation Voltage vs. V_{GE}

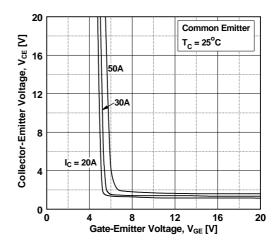


Figure 7. Saturation Voltage vs. V_{GE}

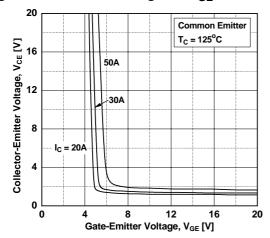


Figure 9. Gate charge Characteristics

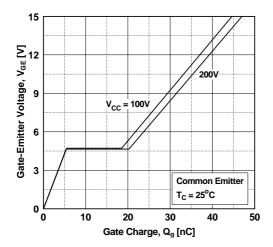


Figure 11. Turn-on Characteristics vs.

Gate Resistance

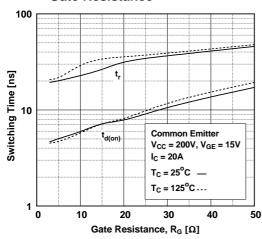


Figure 8. Capacitance Characteristics

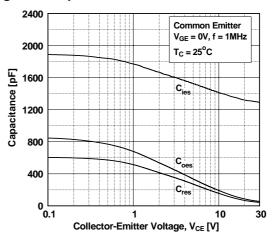


Figure 10. SOA Characteristics

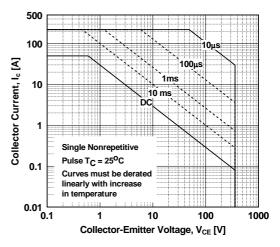


Figure 12. Turn-off Characteristics vs.
Gate Resistance

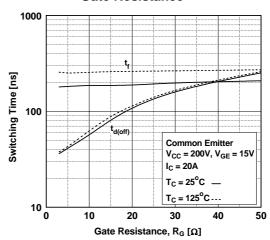


Figure 13. Turn-on Characteristics vs. Collector Current

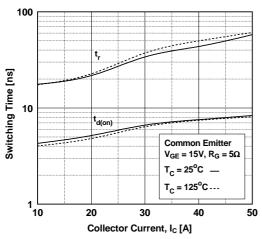


Figure 14. Turn-off Characteristics vs.
Collector Current

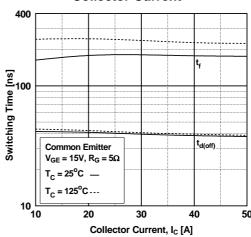


Figure 15. Switching Loss vs. Gate Resistance

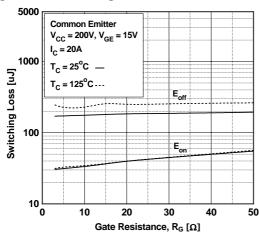


Figure 16. Switching Loss vs. Collector Current

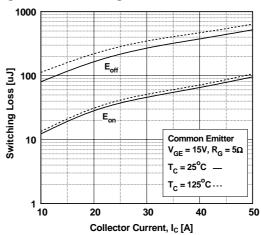
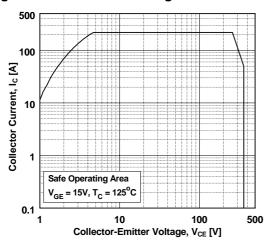
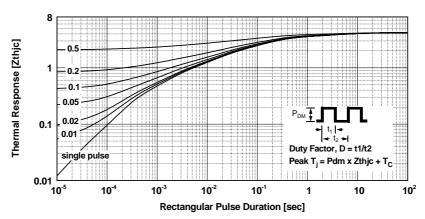


Figure 17. Turn off Switching SOA Characteristics

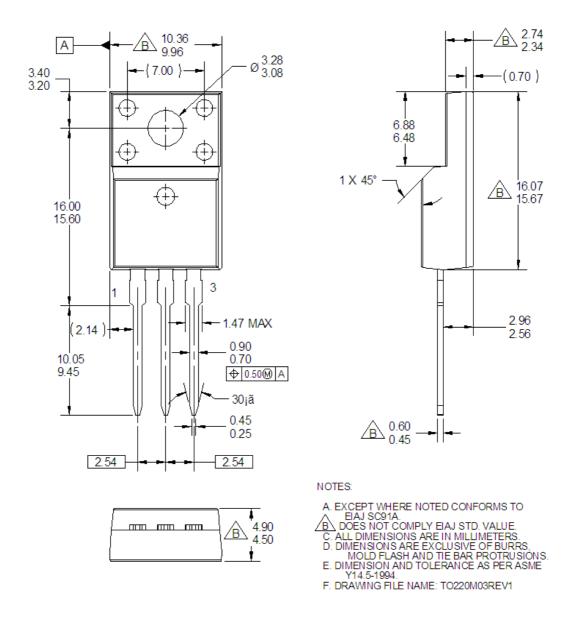






Package Dimensions

TO-220F (Retractable)



* Front/Back Side Isolation Voltage: AC 2700V

Dimensions in Millimeters





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